

Kulicke & Soffa Industries, Inc.

## **Kulicke & Soffa Introduces the APAMA C2W - Chip-to-Wafer Thermo-Compression Bonder**

SINGAPORE--(BUSINESS WIRE)-- Kulicke and Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company") introduces a new addition to the APAMATM Series of highly adaptive Thermo-Compression (TC) Bonders, the C2W (Chip-to-Wafer) bonder. The APAMA C2W is the second in the series to be launched, following the C2S (Chip-to-Substrate) bonder introduced in 2014. The APAMA series TC Bonders deliver industry-leading throughput, placement accuracy, metrology and cost-of-ownership advantages to the high growth Advanced Packaging market.

The APAMA C2W and C2S systems offer fully automated solutions for Thermo-Compression-Bonding (TCB), and a common platform, leveraging an advanced bond head design. The addition of the new dual head C2W system enables the advantages of the unique APAMA high throughput architecture to be applied to 2.5D and 3D packages using silicon or glass interposers. The introduction of the C2W platform combined with the capability of the existing C2S platform, enable the APAMA TCB systems to support assembly for the full range of stacked TSV products. The modular design of the new C2W system also creates a highly adaptable manufacturing platform that is able to address future applications requiring highly accurate placement of die for High Density Fan-Out Wafer Level Packaging (FOWLP). Upon its introduction, the APAMA C2W becomes one of the best performing TC Bonders in the industry with exceptional cost-of-ownership, process control and data integration capability.

This C2W launch further transforms K&S into a leading equipment supplier for the advanced packaging sector. With the acquisition of Assembleon earlier this year, K&S has a complete offering of advanced packaging solutions ranging FOWLP, Wafer Level Packaging (WLP), Flip Chip, System-in-a-Package (SiP), Package-on-Package (PoP), Embedded die and TCB.

Tong Liang Cheam, Kulicke & Soffa's Vice President of the Advanced Packaging Business Line and Corporate Strategy, said, "K&S is proud to add the APAMA C2W to our rapidly expanding portfolio of Advanced Packaging equipment. This new C2W dual head system provides a highly capable manufacturing solution for the most advanced 2.5D and 3D products. As the features and functionalities of ICs increase, there is a trend toward reduced pitch and higher I/O count requiring assembly equipment with much higher accuracy. K&S APAMA solutions are designed from the start with performance and accuracy in mind to enable this next generation of fine pitch products to be bonded with market leading throughput."

The APAMA C2W will debut at the SEMICON Taiwan show at the Taipei Nangang Exhibition Center, K&S Booth #616 Level 4, from September 2-4, 2015.

### **About Kulicke & Soffa**

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. ([www.kns.com](http://www.kns.com))

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